

## Q1 FY2025 (April – June 2024) Financial Announcement

August 8, 2024

#### Agenda:

- Consolidated Financial Summary
   Hiroshi Kawamoto, SVP & GM, Division Officer of Finance Division
- Business Environment and Financial Estimates
   Toshiki Kawai, Representative Director, President & CEO

### Forward Looking Statements

- Disclaimer regarding forward-looking statements Forward-looking statements with respect to TEL's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors, including political and economic situation, semiconductor market conditions, intensification of sales competition, safety and product quality management, intellectual property-related matters and impacts from COVID-19.
- Processing of numbers
   For the amount listed, because fractions are rounded down, there may be the cases where the total for certain account titles does not correspond to the sum of the respective figures for account titles. Percentages are calculated using full amounts, before rounding.
- Foreign exchange risk
   In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.



## Q1 FY2025 Consolidated Financial Summary

August 8, 2024

Hiroshi Kawamoto SVP & GM, Division Officer of Finance Division



## Financial Summary (Quarterly)

(Billion yen)

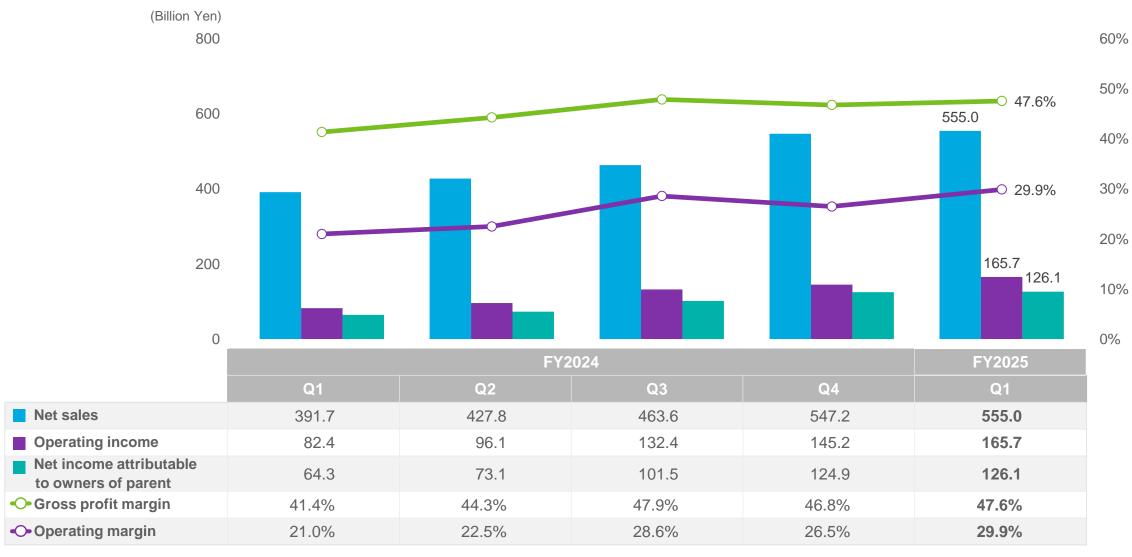
	FY2024				FY2025	vs. Q4	vs. Q1
	Q1	Q2	Q3	Q4	Q1	FY2024	FY2024
Net sales	391.7	427.8	463.6	547.2	555.0	+1.4%	+41.7%
Gross profit Gross profit margin	162.3 41.4%	189.7 44.3%	222.1 47.9%	256.1 46.8%	264.0 47.6%	+3.1% +0.8pts	+62.7% +6.2pts
SG&A expenses	79.8	93.5	89.6	110.8	98.2	-11.4%	+23.0%
Operating income	82.4	96.1	132.4	145.2	165.7	+14.1%	+101.1%
Operating margin	21.0%	22.5%	28.6%	26.5%	29.9%	+3.4pts	+8.9pts
Income before income taxes	83.0	98.1	134.4	157.8	167.2	+5.9%	+101.5%
Net income attributable to owners of parent	64.3	73.1	101.5	124.9	126.1	+1.0%	+96.2%
R&D expenses	43.6	51.0	49.7	58.4	53.4	-8.5%	+22.4%
Capital expenditures	39.3	17.6	31.8	32.9	23.9	-27.2%	-39.1%
Depreciation and amortization	10.6	12.5	13.8	15.3	13.2	-14.0%	+24.5%

<sup>1.</sup> In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.



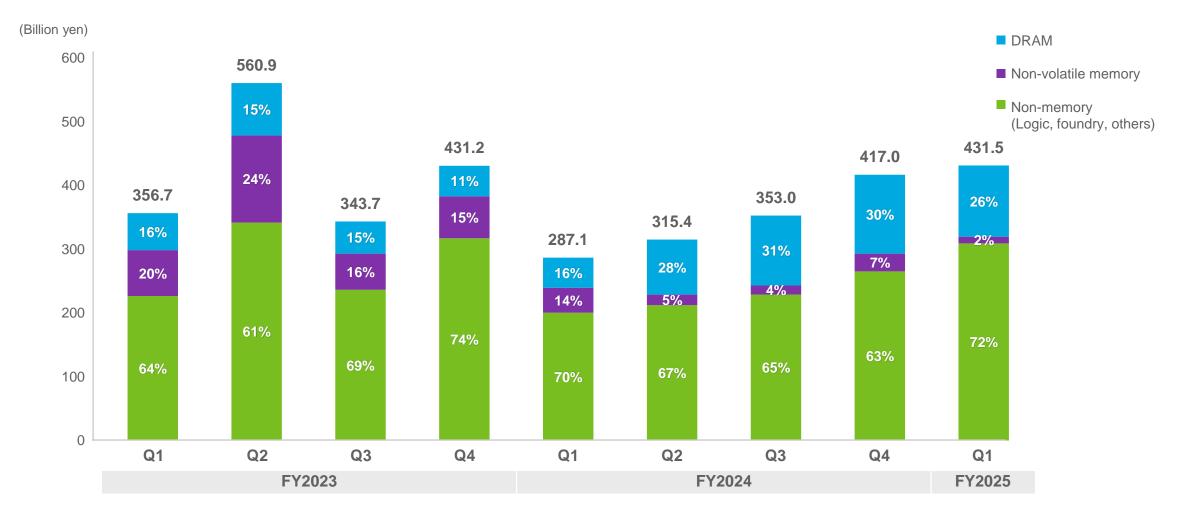
<sup>2.</sup> Profit ratios are calculated using full amounts, before rounding.

### Financial Performance (Quarterly)





## SPE New Equipment Sales by Application (Quarterly)

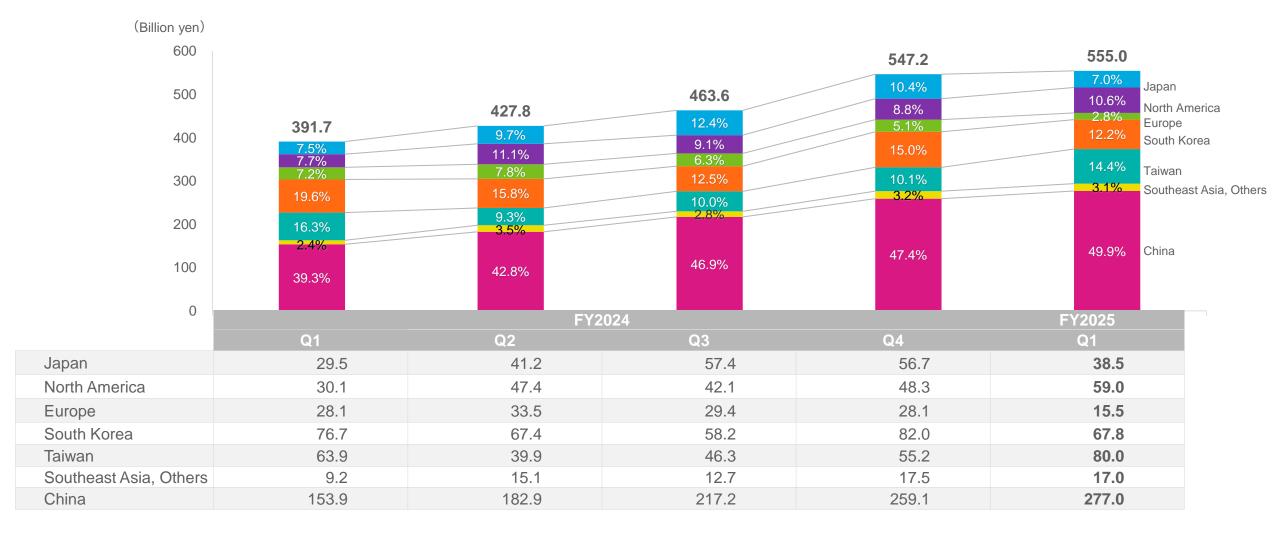


<sup>\*1</sup> SPE: Semiconductor production equipment

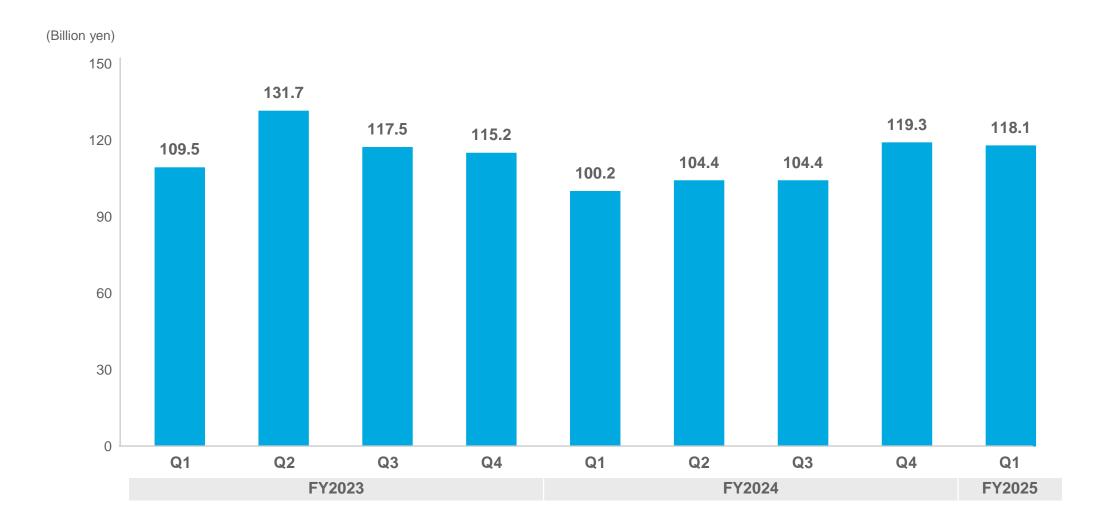


<sup>\*2</sup> Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

## Composition of Net Sales by Region (FY2024 Q1-FY2025 Q1)

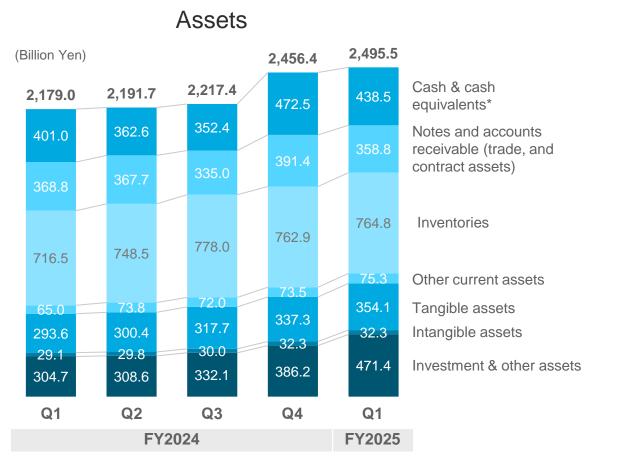


## Field Solutions Sales (Quarterly)





### Balance Sheet (Quarterly)



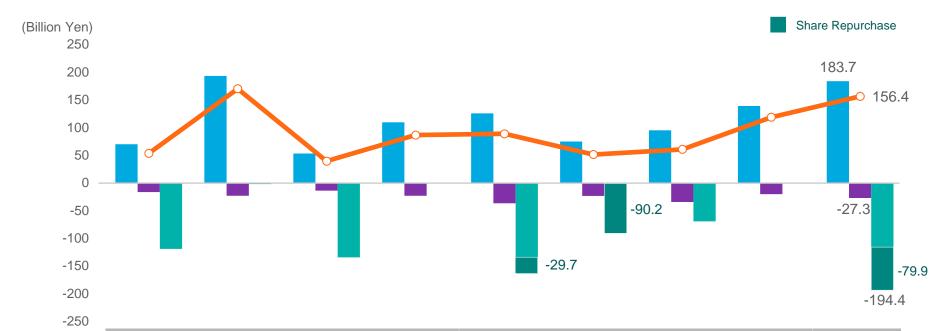
#### Liabilities & Net Assets



<sup>\*</sup>Cash and cash equivalents: "Cash and deposits" + "Short-term investments", etc. ("Securities" in Balance Sheet).

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### Cash Flow (Quarterly)



	FY2023			FY2024				FY2025	
	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1
Cash flow from operating activities	69.9	193.4	53.2	109.6	125.7	74.8	95.0	139.0	183.7
Cash flow from investing activities*1	-16.6	-23.1	-13.8	-23.1	-36.8	-23.4	-34.4	-20.3	-27.3
Cash flow from financing activities	-119.1	-2.1	-134.6	-0.5	-164.1	-90.8	-69.3	-0.6	-194.4
◆ Free cash flow*2	53.3	170.2	39.3	86.5	88.8	51.4	60.6	118.7	156.4
Cash on hand*3	314.6	484.6	387.4	473.1	401.0	362.6	352.4	472.5	438.5

<sup>\*1</sup> Cash flow from investing activities excludes changes in time deposits and short-term investments.

<sup>\*2</sup> Free cash flow = "Cash flow from operating activities" + "Cash flow from investing activities" (excluding changes in "Time deposits" and "Short-term investments").

<sup>\*3</sup> Cash on hand includes "Cash and cash equivalents" + "Time deposits and short-term investments" with original maturities of more than three months.

### Status of Share Repurchase

Completed Share Repurchase by June 30, 2024

Total number of shares acquired
 2,317,000 shares

Total cost of acquisition79,998,958,000 yen

Reference (Resolutions of the Board of Directors' meeting held on May 10, 2024)

Type of shares to be acquired
 Shares of common stock

Total number of shares to be acquired
 Up to 3.5 million shares

(Equivalent to 0.8% of outstanding shares

excluding treasury stock)

Total cost of acquisition
 Up to 80 billion yen

Period of acquisition
 From May 13, 2024 to July 31, 2024



#### Business Environment and Financial Estimates

August 8, 2024

Toshiki Kawai Representative Director, President & CEO



#### Business Environment (WFE Market Outlook as of August 2024)

#### CY2024: Estimating just over \$100B

- Expecting to strong investment in AI servers and steady recovery in the fab utilization rate for PC/smartphone chips
  - DRAM investment to recover on higher demand for DDR5, HBM\*1, etc.
  - Growing needs in advanced logic/foundry, including front-end equipment, packaging, testing, etc.

#### CY2025: Double-digit growth expected

- Recovery in demand amid strong growth of AI servers and rising number of PCs/smartphones with AI
  - In addition to further expansion of DRAM, NAND investment will resume as inventory adjustment progress
  - Advanced logic/foundry, offsetting a lull in investment for mature nodes
- → Expanding business opportunities for TEL amid progress in technological innovations (GAA\*², Backside PDN\*³, HBM, wafer probers for testing in 3D-Integration) for high capacity, ultra-high speed, and low power consumption

<sup>:</sup> Structures that arrange power delivery networks on the backside of silicon wafer



<sup>\*1</sup> HBM (High Bandwidth Memory)

<sup>\*2</sup> GAA (Gate All Around)

<sup>\*3</sup> Backside PDN (Power Delivery Network)

<sup>:</sup> A transistor structure where the channel is surrounded by the gate

### FY2025 Q1 Business Progress

- Both net sales and profit exceeded initial plan
  - Net sales ¥555.0B, operating profit ¥165.7B, operating profit margin 29.9%
- Made good progress in acquiring PORs\* through strategic products
  - Acquired development PORs including conductor etching for DRAM and cleaning equipment for advanced logic
  - Progressing in development and evaluation toward volume production for NAND cryogenic etch and bonders, etc.
- Increase in inquiries for advanced packaging and testing
  - Received a wide range of inquiries (coater/developer, etcher, batch deposition, bonder, prober, etc.)
- Released new products to contributing to innovation in semiconductor technology
  - Single-wafer deposition system "Episode™ Series": Responds to the needs to advance device scaling,
     3D structures and for a greater variety of deposition material
  - Gas cluster beam system "Acrevia™": Features low-damage, ultra-fine line width processing and shape correction, which reduces the cost of EUV patterning processes
- Completed approx. ¥80B share buyback



### FY2025 Financial Estimates



#### FY2025 Financial Estimates

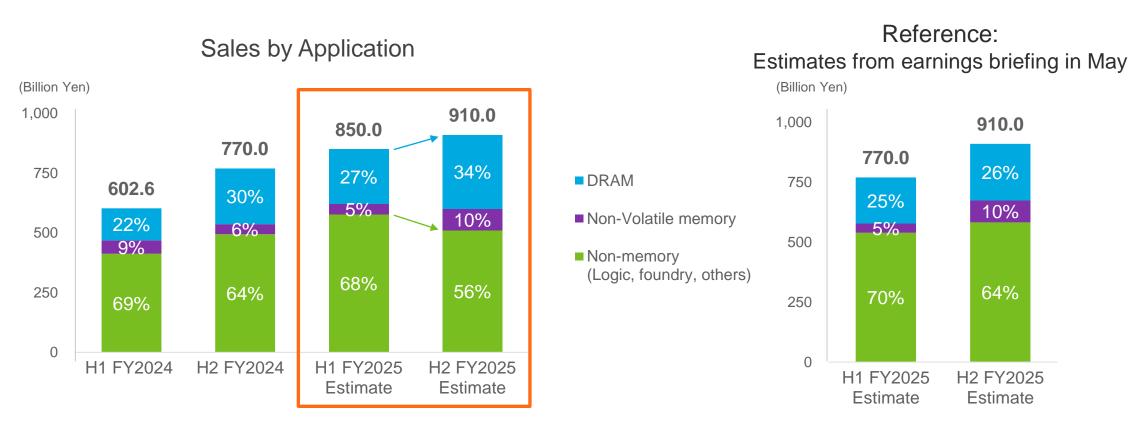
(Billion Yen)

	FY2024	FY2025 (Estimates)								
	(Actual)	H1	H2	Full Year	Full Year Adjustments	Full Year YoY				
Net sales	1,830.5	1,100.0	1,200.0	2,300.0	+100.0	+25.6%				
Gross profit Gross profit margin	830.2 45.4%	504.0 45.8%	568.0 47.3%	1,072.0 46.6%	+50.0 +0.1pts	+29.1% +1.2pts				
SG&A expenses R&D Other than R&D	374.0 202.8 171.1	216.0 121.0 95.0	229.0 132.0 97.0	445.0 253.0 192.0	+5.0 +3.0 +2.0	+19.0% +24.8% +12.2%				
Operating income Operating margin	456.2 24.9%	288.0 26.2%	339.0 28.3%	627.0 27.3%	+45.0 +0.8pts	+37.4% +2.4pts				
Income before income taxes	473.4	290.0	340.0	630.0	+46.0	+33.1%				
Net income attributable to owners of parent	363.9	218.0	260.0	478.0	+33.0	+31.3%				
Net income per share (Yen)	783.75	472.61	-	1,036.94	+75.75	+253.19				

Made upward revisions to estimates based on Q1 results and latest market trend. Expect record-high net sales, GP, GPM, OP, NP, and EPS in FY2025

Investor Relations / August 8, 2024

### FY2025 SPE New Equipment Sales Forecast



Percentages on the graph show the composition ratio of new equipment sales. Field solutions sales are not included.

Updated proportion of sales in logic and memory based on recent market trend

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#### FY2025 R&D Expenses and Capex Plan

#### **New Development Building**

Deposition system, etch system, corporate R&D



Nirasaki-city, Yamanashi Prefecture Established in July 2023

#### **New Development Building**

Coater/developer, cleaning system, bonder



Koshi-city, Kumamoto Prefecture Completion scheduled for summer 2025

#### **Tohoku Production and Logistics Center**

Deposition system



Oshu-city, Iwate Prefecture Completion scheduled for autumn 2025

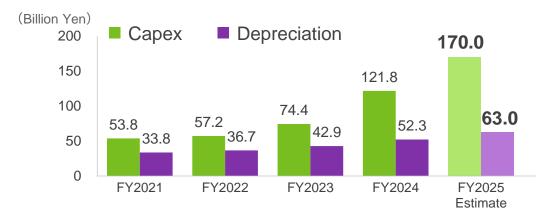
#### **New Development Building**

Etch system



Kurokawa-gun, Miyagi Prefecture Completion scheduled for spring 2025



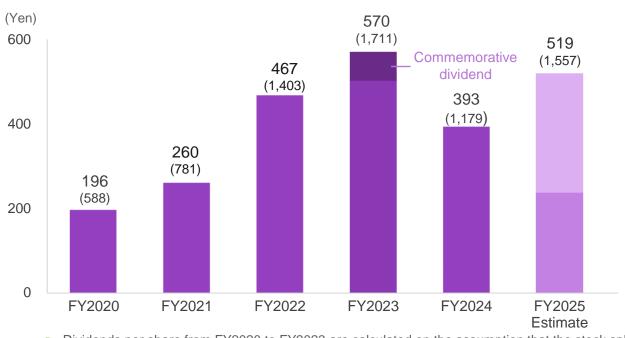


Continue aggressive R&D and capital investments for future growth



#### FY2025 Dividend Forecast

#### Dividend per Share



#### **TEL** shareholder return policy

#### Dividend payout ratio: 50%

Annual DPS of not less than 50 yen\*

We will review our dividend policy if the company does not generate net income for two consecutive fiscal years

We will flexibly consider share buybacks

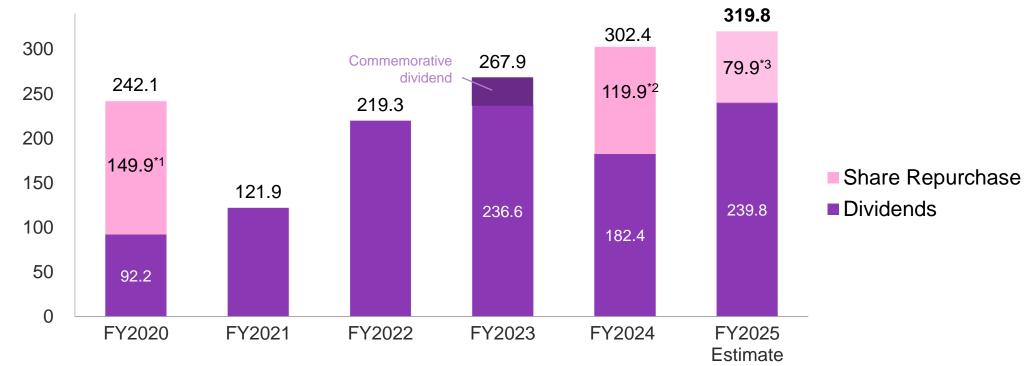
\*Due to the stock split on April 1, 2023, the amount has been changed from 150 yen to 50 yen.

- Dividends per share from FY2020 to FY2023 are calculated on the assumption that the stock split was conducted at the beginning of FY2020.
- FY2023 includes the 60<sup>th</sup> anniversary commemorative dividends.
- Amounts before the stock split are shown in parentheses.

Implemented a 3-for-1 common stock split on April 1, 2023. Full-year dividends are expected to be 519 yen per share

#### **Total Return Amount**

(Billion yen)



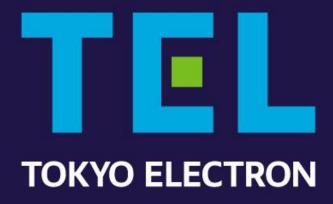
<sup>\*1</sup> https://www.tel.com/news/ir/2020/20200106 001.html

Combined with share buyback, total return amount is expected to be record high

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<sup>\*2</sup> https://www.tel.com/news/ir/2023/de4nhu0000000045-att/20231002\_001\_e.pdf

<sup>\*3</sup> https://www.tel.com/news/ir/2024/tnq6pk00000009m-att/20240701 001 e.pdf



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